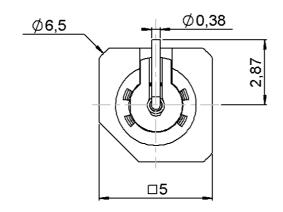
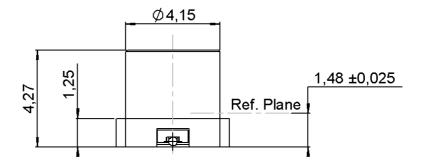
SMOOTH BORE-TAPE AND REEL 500

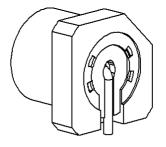
R222.941.700

Series : **SMP-COM**









All dimensions are in mm.

| _ | COMPONENTS | MATERIALS | PLATING (μm) |
|---|-----------------------------------------------------------------|---------------------------------------|-----------------------------|
| | BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS | BRASS BRASS - PEEK - - | NPGR NPGR - - - |
| | | | |

Issue: 1121 C

In the effort to improve our products, we reserve the right to make changes judged to be



SMOOTH BORE-TAPE AND REEL 500

R222.941.700

Series: SMP-COM

PACKAGING

Standard Unit Other 500 Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-12.4*} \;\; \text{GHz} \end{array}$

VSWR 1.10** + 0,0000 x F(GHz) Maxi

Insertion loss $0.12 \sqrt{F(GHz)}$ dB Maxi RF leakage -(NA - F(GHz)) dB Maxi

Voltage rating 335 Veff Maxi Dielectric withstanding voltage Insulation resistance 500 Veff mini 5000 M Ω mini

ENVIRONMENTAL

Operating temperature -55/+125 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

* ROS 1.35 at 12.4GHz

**ROS at 6GHz

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

6.8 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **0,3280** g

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R222.941.700

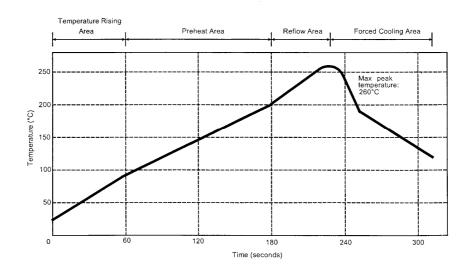
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SOLDER PROCEDURE

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of $150\ \text{micromm}$ ($5.850\ \text{microinch}$). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



| Parameter | Value | Unit |
|----------------------------------|----------|--------|
| Temperature rising Area | 1 - 4 | °C/sec |
| Max Peak Temperature | 260 | °C |
| Max dwell time @260°C | 10 | sec |
| Min dwell time @235°C | 20 | sec |
| Max dwell time @235°C | 60 | sec |
| Temperature drop in cooling Area | -1 to -4 | °C/sec |
| Max dwell time above 100°C | 420 | sec |

Issue: 1121 C In the effort to improve our products, we reserve the right to make changes judged to be necessary.

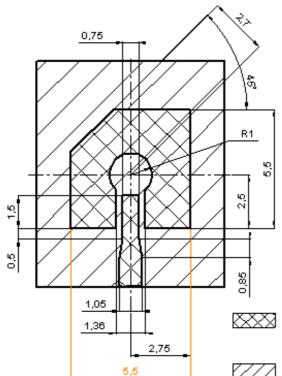


SMOOTH BORE-TAPE AND REEL 500

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STANDARD PAD(For ROGERS 4350)



COPLANAR LINE

Pattern and signal are on the same side.

Thickness of PCB: 1.6mm

The material of PCB is the epoxy resin of

glass fabrics bacs (ER:4.8).

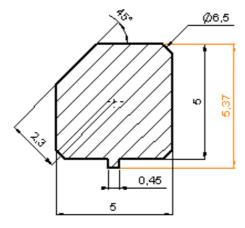
The solder resist should be printed exept for

the land pattern on the PCB.

Lands for solder paste

Ground + Varnish

SHADOW OF RECEPTACLE FOR VIDEO CAMERA



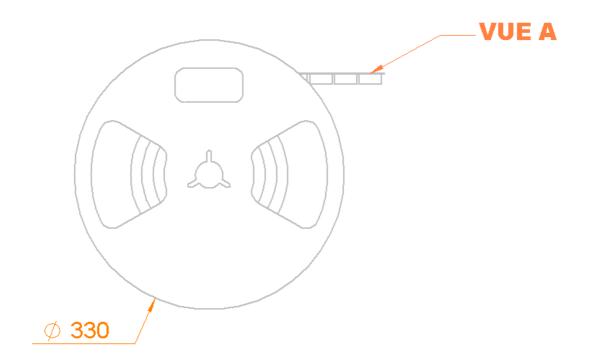
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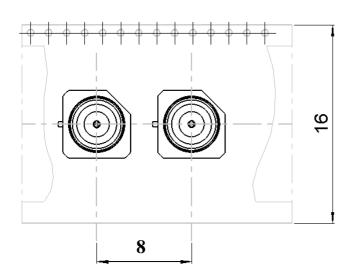
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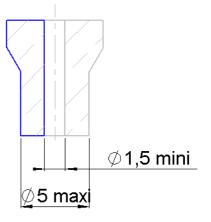
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Vue suivant A



AIR SUNCTION



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